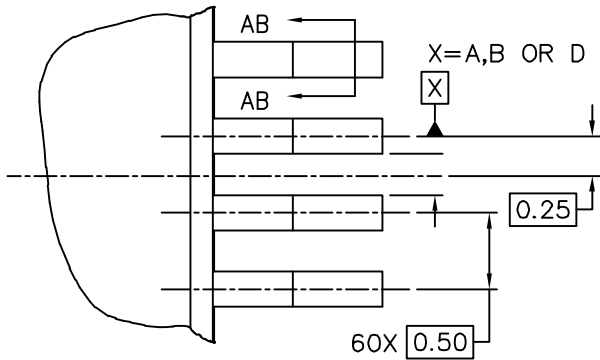
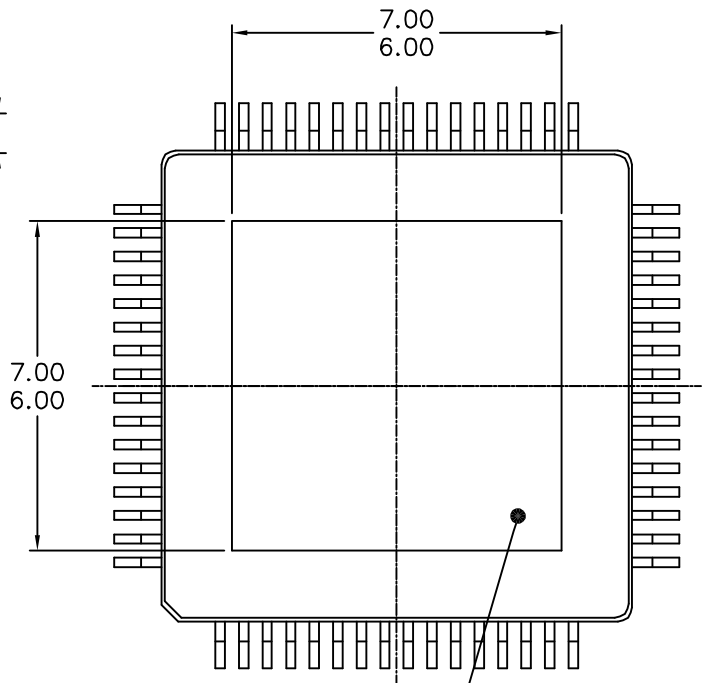


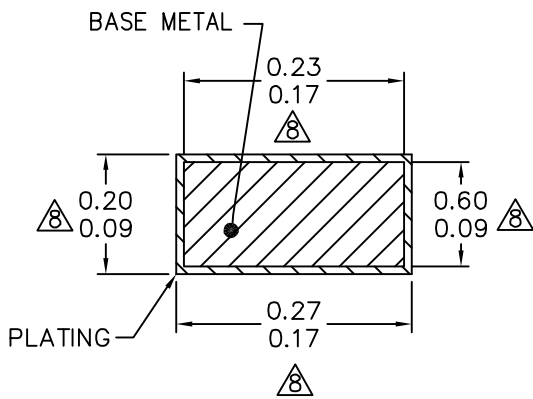
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TITLE: 64 LD LQFP, 10 X 10 X 1.4 PKG, 0.5 PITCH, EXPOSED PAD	DOCUMENT NO: 98ARH98426A	REV: B
	STANDARD: JEDEC MS-026 BCD-HD	
	SOT1510-3	24 DEC 2015



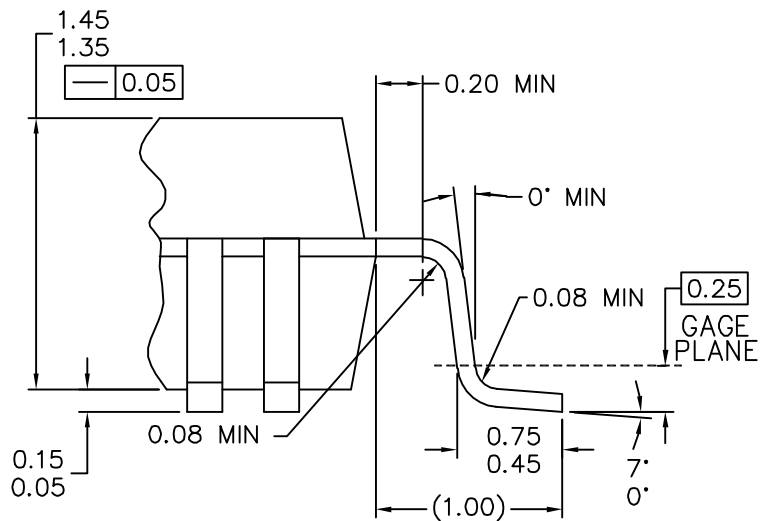
VIEW Y



VIEW J-J



SECTION AB-AB



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	STANDARD: JEDEC MS-026 BCD-HD	
	SOT1510-3	24 DEC 2015



NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.

④ DIMENSIONS TO BE DETERMINED AT SEATING PLANE C

⑤ DIMENSION DOES NOT INCLUDE DAMBER PROTRUSION. ALLOWABLE DAMBER PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE MAXIMUM DIMENSION BY MORE THAN 0.08 mm. DAMBER CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07 mm.

⑥ DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 mm PER SIDE. DIMENSIONS ARE MAXIMUM PLASTIC BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH.

⑦ EXACT SHAPE OF EACH CORNER IS OPTIONAL.

⑧ THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 mm AND 0.25 mm FROM THE LEAD TIP.

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